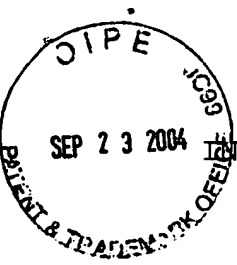


IFW



PT-03-008

September 20, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/807,036 03/23/04 |
Thomas Aisenbrey
LOW COST THERMAL MANAGEMENT DEVICE
OR HEAT SINK USING CONDUCTIVE
PLASTICS OR CONDUCTIVE COMPOSITES
| _____ |

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on September 21, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date SBQ 9/21/04

U.S. Patent 5,849,130 to Browne, "Method of Making and Using Thermally Conductive Joining Film," discloses a joining film composed of a thin polymeric composite sheet material containing orientated thermally conductive fibers, processes for manufacturing this film and use of this film in heat transfer joints.

U.S. Patent 6,364,009 to MacManus et al., "Cooling Devices," discloses a cooling apparatus for cooling an electrical device using a flow of coolant comprising a cooling unit.

European Patent Application EP 0 506 509 A to Sono et al., "Semiconductor Device Having Radiation Part and Method of Producing the Same," discusses a semiconductor device having a radiation part for radiating heat and a method of producing such a semiconductor device.

International Patent Publication WO 03/017365 A to Flint et al., "Thermal Transfer Devices," discloses thermal transfer devices, including heat pipes and vapor chambers.

U.S. Patent 6,397,941 to McCullough, "Net-shape Molded Heat Exchanger," discloses apparatuses for dissipating heat generated by such objects.

INT-03-008

European Patent Application EP 1 265 281 A to Tobita et al., "Thermally Conductive Molded Article and Method of Making the Same," discloses a thermally conductive molded article that has excellent thermal conductivity and a method of making the same.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over the printed name.

Stephen B. Ackerman,
Reg. No. 37761

~~SECRET~~ TO-1449

<p> Doctor Number (Optional) _____ </p>

Application Number

INT-03-008

10 | 807,036

Applicant

Thomas Aisenbrey

Filing Date: 11/11/2011

3/23/04

Group Art Unit

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

U. S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
EP 0 50 6 50 9 A	3/16/92	European Patent App.	H01L	23/055			
WO 03 / 01 7 36 5 A	8/17/01	Int'l Patent	H01L	23/34			
EP 1 265 28 1 A	6/5/02	European Patent App.	H01L	23/373			

OTHER DOCUMENTS (Including Author, Title, Date, Portion or Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.